



Material Content Data Sheet



Sales Product Name		BSZ065N03LS		Issued		26. September 2017		
MA#		MA001015338						
Package		PG-TSDSON-8-25		Weight*		35.30 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.182	0.52	0.52	5156	5156
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		70	
	non noble metal	zinc	7440-66-6	0.010	0.03		279	
	non noble metal	iron	7439-89-6	0.197	0.56		5574	
wire	non noble metal	copper	7440-50-8	7.988	22.63	23.23	226334	232257
	noble metal	gold	7440-57-5	0.030	0.09	0.09	856	856
encapsulation	organic material	carbon black	1333-86-4	0.038	0.11		1087	
	plastics	epoxy resin	-	1.977	5.60		56004	
	inorganic material	silicondioxide	60676-86-0	17.176	48.66	54.37	486634	543725
leadfinish	non noble metal	tin	7440-31-5	0.400	1.13	1.13	11339	11339
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	576	576
solder	noble metal	silver	7440-22-4	0.008	0.02		228	
	non noble metal	tin	7440-31-5	0.006	0.02		182	
	non noble metal	lead	7439-92-1	0.307	0.87	0.91	8701	9111
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		33	
	non noble metal	zinc	7440-66-6	0.005	0.01		133	
	non noble metal	iron	7439-89-6	0.094	0.27		2663	
	non noble metal	copper	7440-50-8	3.816	10.81	11.09	108116	110945
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		26	
	non noble metal	zinc	7440-66-6	0.004	0.01		103	
	non noble metal	iron	7439-89-6	0.073	0.21		2065	
	non noble metal	copper	7440-50-8	2.959	8.38	8.60	83841	86035
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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